

**RoHS Compliant Product**  
A suffix of "C" specifies halogen and lead-free

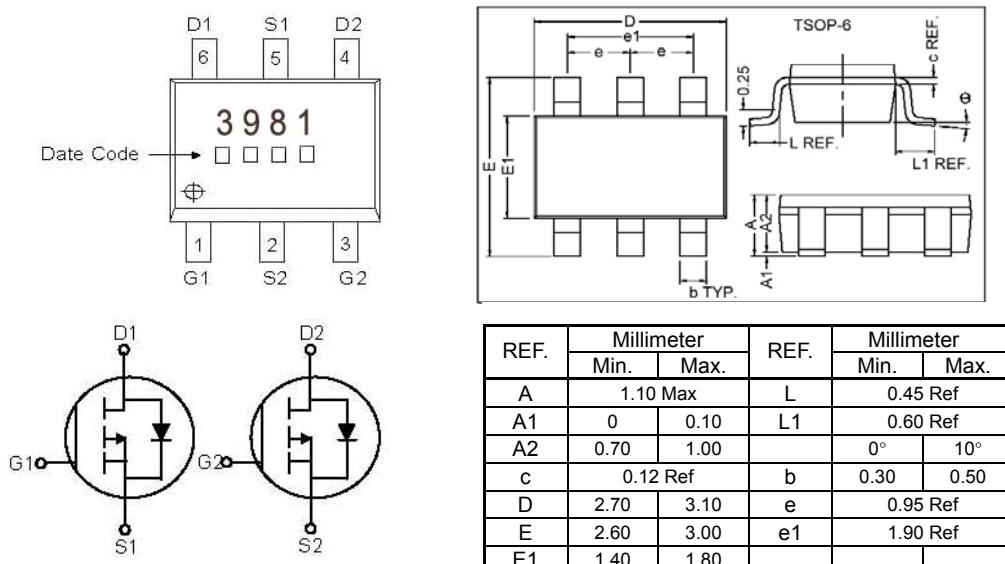
## DESCRIPTION

The STT3981 utilized advance processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device. The STT3981 is universally used for all commercial-industrial applications.

## FEATURES

- Low On-Resistance
- Low Gate Charge

## PACKAGE DIMENSIONS



## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current <sup>3</sup>	$I_D @ T_A=25^\circ C$ $I_D @ T_A=70^\circ C$	-1.6 -1.3	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-8	A
Power Dissipation	$P_D @ T_A=25^\circ C$	0.8	W
Linear Derating Factor		0.006	W/ $^\circ C$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	$^\circ C$

## THERMAL DATA

Parameter	Symbol	Ratings	Unit
Thermal Resistance Junction-ambient <sup>3</sup> (Max)	$R_{0JA}$	150	$^\circ C/W$

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise specified)**

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	-	-	V	V <sub>GS</sub> = 0, I <sub>D</sub> =250 uA
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.4	-	-1.1	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250 uA
Gate Leakage Current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> = ±8 V
Drain-Source Leakage Current (T <sub>j</sub> =25°C)	I <sub>DSS</sub>	-	-	-1	uA	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0
Drain-Source Leakage Current (T <sub>j</sub> =70°C)		-	-	-20		V <sub>DS</sub> = -16 V, V <sub>GS</sub> = 0
Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	100	150	mΩ	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -1.9 A
		-	160	210		V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -1.6 A
		-	260	300		V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -0.7 A
Forward Transconductance	g <sub>fs</sub>	-	4	-	S	V <sub>DS</sub> = -5V, I <sub>D</sub> = -1.9A
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	-	-0.84	-1.1	V	I <sub>S</sub> = -1.0A, V <sub>GS</sub> = 0V
<b>Dynamic</b>						
Total Gate Charge <sup>2</sup>	Q <sub>g</sub>	-	6	7.5	nC	I <sub>D</sub> = -1.9 A V <sub>DS</sub> = -10 V V <sub>GS</sub> = -4.5 V
Gate-Source Charge	Q <sub>gs</sub>	-	0.52	-		
Gate-Drain ("Miller") Charge	Q <sub>gd</sub>	-	1.02	-		
Turn-on Delay Time <sup>2</sup>	T <sub>d(on)</sub>	-	50	65	nS	V <sub>DS</sub> = -10 V I <sub>D</sub> = -1 A V <sub>GEN</sub> = -4.5 V R <sub>G</sub> = 6 Ω R <sub>L</sub> = 10 Ω
Rise Time	T <sub>r</sub>	-	40	60		
Turn-off Time	T <sub>d(off)</sub>	-	168	180		
Fall Time	T <sub>f</sub>	-	64	75		
Input Capacitance	C <sub>iss</sub>	-	450	-	pF	V <sub>GS</sub> = 0 V V <sub>DS</sub> = -15 V f = 1.0 MHz
Output Capacitance	C <sub>oss</sub>	-	60	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	47	-		

Notes: 1. Pulse width limited by maximum junction temperature.

2. Pulse width  $\leq$  300us, duty cycle  $\leq$  2%.

3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board; 180 °C/W when mounted on minimum copper pad.

## CHARACTERISTIC CURVES

